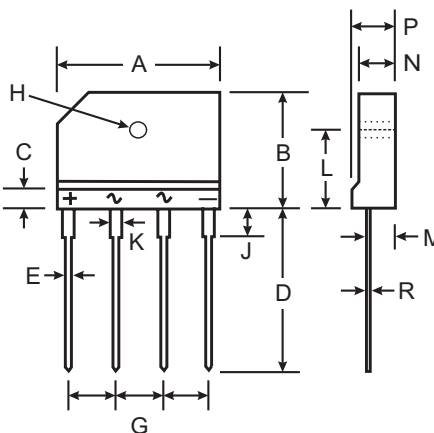


Features

- Glass Passivated Die Construction
- High Case Dielectric Strength of 1500V_{RMS}
- Low Reverse Leakage Current
- Surge Overload Rating to 170A Peak
- Ideal for Printed Circuit Board Applications
- UL Listed Under Recognized Component Index, File Number E94661
- **Lead Free Finish, RoHS Compliant (Note 4)**

Mechanical Data

- Case: KBJ
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Finish — Tin. Plated Leads, Solderable per MIL-STD-202, Method 208 (e3)
- Polarity: Molded on Body
- Mounting: Through Hole for #6 Screw
- Mounting Torque: 5.0 in-lbs Maximum
- Ordering Information: See Last Page
- Marking: Type Number
- Weight: 4.6 grams (approximate)



KBJ		
Dim	Min	Max
A	24.80	25.20
B	14.70	15.30
C	4.00 Nominal	
D	17.20	17.80
E	0.90	1.10
G	7.30	7.70
H	3.10 Ø	3.40 Ø
J	3.30	3.70
K	1.50	1.90
L	9.30	9.70
M	2.50	2.90
N	3.40	3.80
P	4.40	4.80
R	0.60	0.80
All Dimensions in mm		

Maximum Ratings and Electrical Characteristics @ T_A = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.
 For capacitive load, derate current by 20%.

Characteristic	Symbol	KBJ 6005G	KBJ 601G	KBJ 602G	KBJ 604G	KBJ 606G	KBJ 608G	KBJ 610G	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Working Peak Reverse Voltage	V _{RWM}								
DC Blocking Voltage	V _R								
RMS Reverse Voltage	V _{R(RMS)}	35	70	140	280	420	560	700	V
Average Rectified Output Current @ T _C = 110°C	I _O	6.0							A
Non-Repetitive Peak Forward Surge Current, 8.3 ms single half-sine-wave superimposed on rated load	I _{FSM}	170							A
Forward Voltage per element @ I _F = 3.0A	V _{FM}	1.0							V
Peak Reverse Current @ T _C = 25°C	I _{RM}	5.0							µA
at Rated DC Blocking Voltage @ T _C = 125°C		500							
I ² t Rating for Fusing (t < 8.3ms) (Note 3)	I ² t	120							A ² s
Typical Total Capacitance per Element (Note 1)	C _T	80							pF
Typical Thermal Resistance (Note 2)	R _{θJC}	1.5							°C/W
Operating and Storage Temperature Range	T _j , T _{STG}	-65 to +150							°C

- Notes:
1. Measured at 1.0 MHz and applied reverse voltage of 4.0V DC.
 2. Thermal resistance from junction to case per element. Unit mounted on 75 x 75 x 1.6mm aluminum plate heat sink.
 3. Non-repetitive, for t > 1ms and < 8.3ms.
 4. RoHS revision 13.2.2003. Glass and High Temperature Solder Exemptions Applied, see EU Directive Annex Notes 5 and 7.

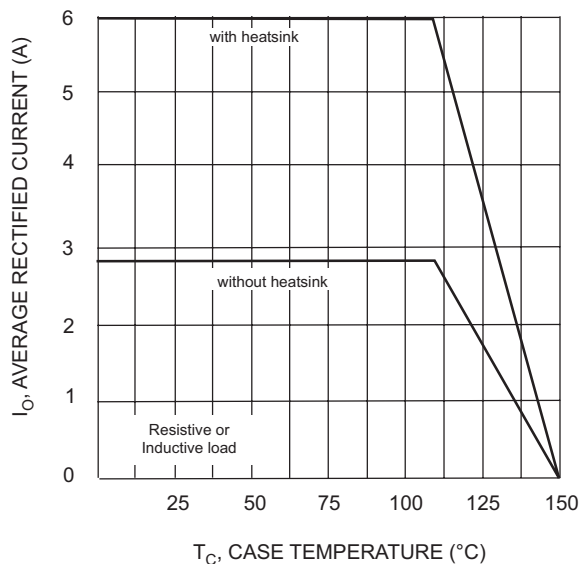


Fig. 1 Forward Current Derating Curve

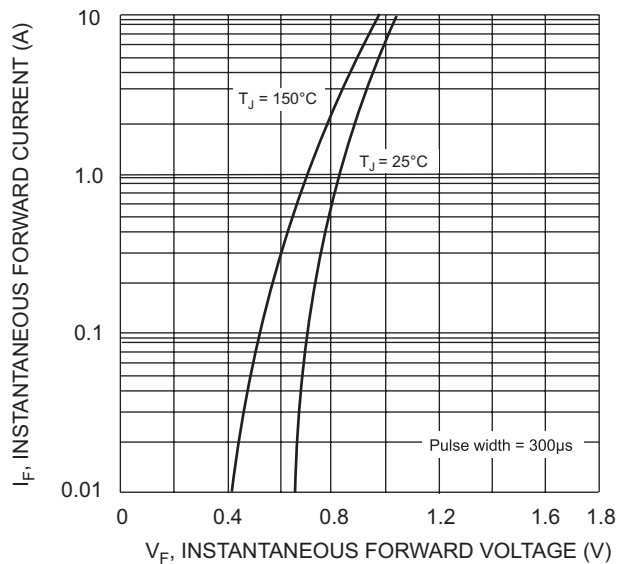


Fig. 2 Typical Forward Characteristics

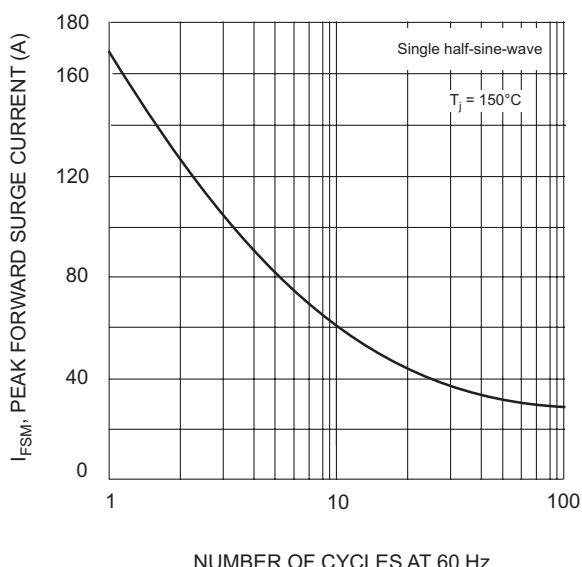


Fig. 3 Max Non-Repetitive Surge Current

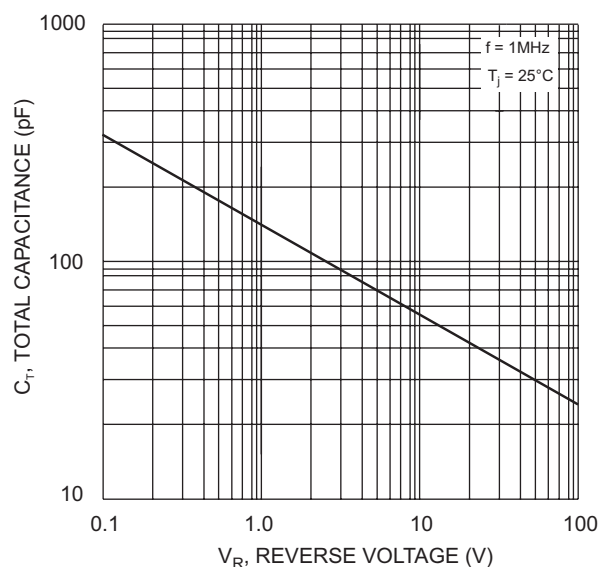


Fig. 4 Typical Total Capacitance, Per Element

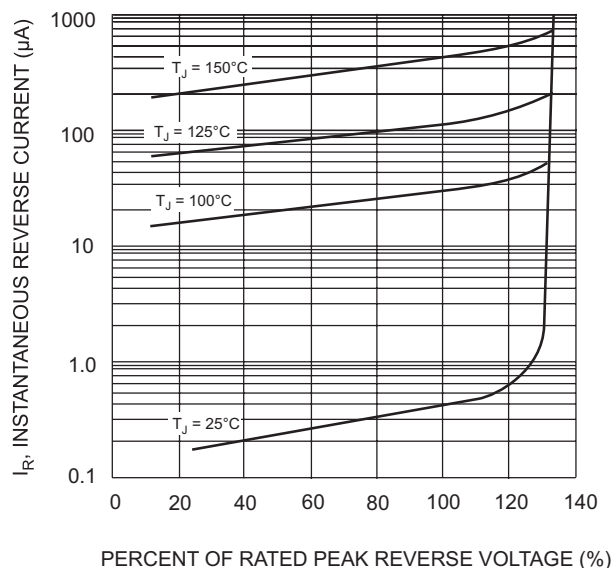


Fig. 5 Typical Reverse Characteristics

Ordering Information (Note 5)

Device	Packaging	Shipping
KBJ6005G	KBJ	20/Tube
KBJ601G	KBJ	20/Tube
KBJ602G	KBJ	20/Tube
KBJ604G	KBJ	20/Tube
KBJ606G	KBJ	20/Tube
KBJ608G	KBJ	20/Tube
KBJ610G	KBJ	20/Tube

Notes: 5. For packaging details, visit our website at <http://www.diodes.com/datasheets/ap2008.pdf>.

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